Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4	dry adj etch$3 same (arc or anti-reflective adj layer) same conductive adj layer same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:47
S2	649578	baek, i.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:04
S3	68	baek-i-h.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:47
S4	60	baek-i.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:06
S5	0	dry adj etch$3 same (arc or anti-reflective adj layer) and nitric adj acid same copper and cmp with barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:50
S6	0	dry adj etch$3 same (arc or antireflective adj layer) and nitric adj acid same copper and cmp with barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:09
S7	2	dry adj etch$3 same (arc or antireflective adj layer) and wet adj etch$3 same copper and cmp with barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:17
S8	0	dry adj etch$3 same (arc or antireflective adj layer) and acid same copper and cmp with barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:18
S9	0	dry adj etch$3 same (arc or antireflective adj layer) and acid same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:18

S76	24	wet adj etch$3 same copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:49
S77	17	wet adj etch$3 same aluminum and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:54
S78	3	sulfuric adj acid same aluminum and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 15:02
S79	10	sulfuric adj acid same copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:49
S80	52	wet adj etch$3 same (copper or aluminum or tungsten or conuductive) and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 15:11
S81	16	wet adj etch$3 with (copper or aluminum or tungsten or conuductive) and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 15:11
S82	77	baek-i-h.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:47
S83	4	dry adj etch$3 same (arc or anti-reflective adj layer) same conductive adj layer same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:47
S84	2488	(438/622).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:47
S85	384	(438/636).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48

S86	1720	(438/706).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S87	415	(438/704).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S88	5526	nitric adj acid same copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:48
S89	3779	cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:48
S90	89	S88 and S89	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:48
S91	415	(438/704).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S92	550	(438/690).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:49
S93	25	wet adj etch$3 same copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:49
S94	10	sulfuric adj acid same copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:49
S95	4	nitric adj acid same copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:49

S10	3	dry adj etch$3 same (arc or antireflective adj layer) and wet adj etch$3 same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:21
S11	1	dry adj etch$3 same (arc or anti-reflection adj layer) and wet adj etch$3 same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:21
S12	1	dry adj etch$3 same (arc or anti-reflection adj layer or arl) and wet adj etch$3 same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:21
S13	5	dry adj etch$3 same (arc or anti-reflection adj layer) same conductive adj layer same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 13:26
S14	1	2003-054538.NRAN.	DERWENT	OR	ON	2005/03/01 13:24
S15	1	2003-054538	DERWENT	OR	ON	2005/03/01 13:25
S16	944	dongbu adj electronics	DERWENT	OR	ON	2005/03/01 13:25
S17	1	dongbu adj electronics and arc and copper	DERWENT	OR	ON	2005/03/01 13:25
S18	32	dongbu adj electronics and copper	DERWENT	OR	ON	2005/03/01 13:25
S19	0	dry adj etch$3 same (arc or anti-reflective adj layer) and nitric adj acid same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 13:51
S20	10	etch$3 same (arc or anti-reflective adj layer) and acid same copper and cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 14:39
S21	361	(438/636).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:47
S22	1582	(438/622).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:47

S23	1087	(438/706).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S24	3	S21 and S23 and copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:40
S25	392	(438/704).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S26	0	S21 and S25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:35
S27	727	dry adj etch and (arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:41
S28	358	dry adj etch$3 same (arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:41
S29	5282	nitric adj acid same copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:41
S30	0	S28 and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:42
S31	3342	cmp same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:47
S32	71	S29 and S31	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/21 17:48

S33	1	S29 and S31 and (arl or arc)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:43
S34	4606	polish$3 same barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:47
S35	2497	polish$3 with barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:47
S36	77	S35 and S29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:47
S37	3	S35 and S29 and (antireflect$3 or arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:50
S38	1141	tungsten same sulphuric adj acid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:50
S39	15	S38 and S35	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:51
S40	0	S38 and S35 and (antireflect$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:51
S41	1321	S38 and S35 and arc or arl	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:51
S42	0	S38 and S35 and (arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:54

S43	4017	etch$3 with (antireflect$3 or arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:55
S44	497	dry adj etch$3 with (antireflect$3 or arc or arl)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:56
S45	1978	wet adj etch$3 with (copper or tungsten or aluminum)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:56
S46	53	S35 and S45	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:57
S47	10	S46 and S43	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/01 15:57
S48	9	"6426298"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 13:22
S49	1	"6426298".PN.	USPAT; USOCR	OR	ON	2005/03/20 13:22
S50	2	("6518206").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 13:25
S51	41	dry adj etch$3 same (arc or anti-reflection adj layer) and conductive adj layer and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 13:26
S52	55	dry adj etch$3 same (arc or anti-reflection adj layer) and copper and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:08

S53	3	dry adj etch$3 same (arc or anti-reflection adj layer) and wet same etch$3 same copper and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 13:46
S54	20	(arc or anti-reflection adj layer) and wet adj etch$3 with (copper or aluminum) and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:08
S55	3	(arc or anti-reflection adj layer) same wet adj etch$3 with (copper or aluminum) and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:17
S56	394	(438/704).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S57	1419	(438/689).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:18
S58	517	(438/690).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/21 17:48
S59	384	(438/754).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/20 14:18
S60	29	S59 and copper same nitric with acid	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:23
S61	0	S59 and copper and barrier adj layer and antireflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:25
S62	0	S59 and aluminum and barrier adj layer and antireflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:24

S63	81	S59 and aluminum and barrier adj layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:24
S64	6	S59 and aluminum and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:24
S65	7	S59 and copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:31
S66	42974	wet adj etch$3 copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:31
S67	5	wet adj etch$3 with copper and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:43
S68	0	wet adj etch$3 with alcu and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:34
S69	5	wet adj etch$3 with aluminum and barrier adj layer and anti-reflective	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:39
S70	1	"5920799".PN.	USPAT; USOCR	OR	ON	2005/03/20 14:36
S71	1	"5834805".PN.	USPAT; USOCR	OR	ON	2005/03/20 14:36
S72	1	"5827437".PN.	USPAT; USOCR	OR	ON	2005/03/20 14:36
S73	1	"5827437".PN.	USPAT; USOCR	OR	ON	2005/03/20 14:39
S74	1	"5801082".PN.	USPAT; USOCR	OR	ON	2005/03/20 14:39
S75	18	"5827437"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/20 14:39